

T-45-07

CD4032B, CD4038B Types

CMOS Triple Serial Adders

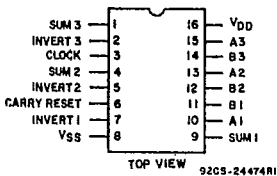
High-Voltage Types (20-Volt Rating)
Positive Logic Adder - CD4032B
Negative Logic Adder - CD4038B

The RCA-CD4032B and CD4038B types consist of three serial adder circuits with common CLOCK and CARRY-RESET inputs. Each adder has provisions for two serial DATA INPUT signals and an INVERT command signal. When the command signal is a logical "1", the sum is complemented. Data words enter the adder with the least significant bit first; the sign bit trails. The output is the MOD 2 sum of the input bits plus the carry from the previous bit position. The carry is only added at the positive-going clock transition for the CD4032B or at the negative-going clock for the CD4038B, thus, for spike-free operation the input data transitions should occur as soon as possible after the triggering edge.

The CARRY is reset to a logical "0" at the end of each word by applying a logical "1" signal to a CARRY-RESET input one-bit-position before the application of the first bit of the next word.

The CD4032B and CD4038B types are supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic packages (E suffix), 16-lead ceramic flat packages (K suffix), and in chip form (H suffix).

CD4032B, CD4038B
TERMINAL DIAGRAM



Features:

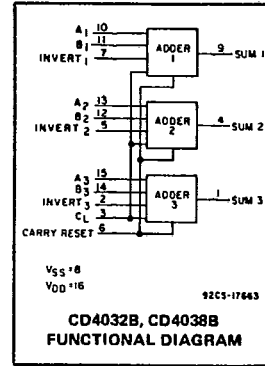
- Invert inputs on all adders for sum complementing applications
- Fully static operation. . . . dc to 10 MHz (typ.) @ $V_{DD} = 10\text{ V}$
- Single-phase clocking
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package-temperature range)

- 1 V at $V_{DD} = 5\text{ V}$
- 2 V at $V_{DD} = 10\text{ V}$
- 2.5 V at $V_{DD} = 15\text{ V}$

- Meets all requirements of JEDEC Tentative Standard No. 13A, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications:

- Serial arithmetic units
- Digital correlators
- Digital datalink computers
- Flight control computers
- Digital servo control systems



MAXIMUM RATINGS, Absolute-Maximum Values:

- DC SUPPLY-VOLTAGE RANGE, (V_{DD}) (Voltages referenced to V_{SS} Terminal) -0.5 to +20 V
- INPUT VOLTAGE RANGE, ALL INPUTS -0.5 to $V_{DD} + 0.5\text{ V}$
- DC INPUT CURRENT, ANY ONE INPUT $\pm 10\text{ mA}$
- POWER DISSIPATION PER PACKAGE (P_D):
 - For $T_A = -40$ to $+60^\circ\text{C}$ (PACKAGE TYPE E) 500 mW
 - For $T_A = +60$ to $+85^\circ\text{C}$ (PACKAGE TYPE E) Derate Linearly at 12 mW/ $^\circ\text{C}$ to 200 mW
 - For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPES D, F, K) 500 mW
 - For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPES D, F, K) Derate Linearly at 12 mW/ $^\circ\text{C}$ to 200 mW
- DEVICE DISSIPATION PER OUTPUT TRANSISTOR
 - For $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$ 100 mW
- OPERATING-TEMPERATURE RANGE (T_A):
 - PACKAGE TYPES D, F, K, H -55 to $+125^\circ\text{C}$
 - PACKAGE TYPE E -40 to $+85^\circ\text{C}$
- STORAGE TEMPERATURE RANGE (T_{stg}) -65 to $+150^\circ\text{C}$
- LEAD TEMPERATURE (DURING SOLDERING):
 - At distance $1/16 \pm 1/32$ inch ($1.59 \pm 0.79\text{ mm}$) from case for 10 s max. $+265^\circ\text{C}$

RECOMMENDED OPERATING CONDITIONS at $T_A = 25^\circ\text{C}$, Unless Otherwise Specified

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

CHARACTERISTIC	V_{DD}	Min.	Max.	UNITS
Supply Voltage Range (at $T_A = \text{Full Package-Temperature Range}$)		3	18	V
Clock Input Frequency, f_{CL}	5	-	2.5	MHz
	10	-	5	
	15	-	7.5	
Clock Input Rise or Fall Time, t_{rCL}, t_{fCL}	5	-	500	μs
	10	-	500	
	15	-	500	
Data Input Set-Up Time, Clock to A or B Inputs, t_{SU}	5	200	-	ns
	10	80	-	
	15	60	-	

CD4032B, CD4038B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNIT
	V _O (V)	V _{IN} (V)	V _{DD} (V)	Values at -55, +25, +125 Apply to D, F, K, H, Packages				Values at -40, +25, +85 Apply to E Package			
				-55	-40	+85	+125	+25			
				Min.	Typ.	Max.					
Quiescent Device Current, I _{DD} Max.	-	0,5	5	5	5	150	150	-	0.04	5	μA
	-	0,10	10	10	10	300	300	-	0.04	10	
	-	0,15	15	20	20	600	600	-	0.04	20	
	-	0,20	20	100	100	3000	3000	-	0.08	100	
Output Low (Sink) Current, I _{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	-	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-	
Output High (Source) Current, I _{OH} Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage: Low-Level, V _{OL} Max.	-	0,5	5	0.05				-	0	0.05	V
	-	0,10	10	0.05				-	0	0.05	
	-	0,15	15	0.05				-	0	0.05	
Output Voltage: High-Level, V _{OH} Min.	-	0,5	5	4.95				4.95	5	-	V
	-	0,10	10	9.95				9.95	10	-	
	-	0,15	15	14.95				14.95	15	-	
Input Low Voltage, V _{IL} Max.	0.5, 4.5	-	5	1.5				-	-	1.5	V
	1, 9	-	10	3				-	-	3	
	1.5, 13.5	-	15	4				-	-	4	
Input High Voltage, V _{IH} Min.	0.5, 4.5	-	5	3.5				3.5	-	-	V
	1, 9	-	10	7				7	-	-	
	1.5, 13.5	-	15	11				11	-	-	
Input Current, I _{IN} Max.	-	0,18	18	±0.1	±0.1	±1	±1	-	±10 ⁻⁵	±0.1	μA

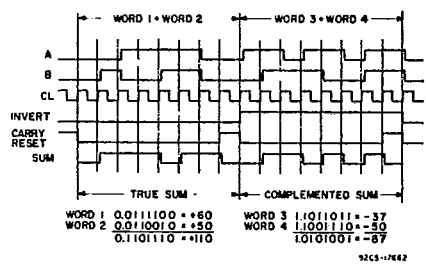
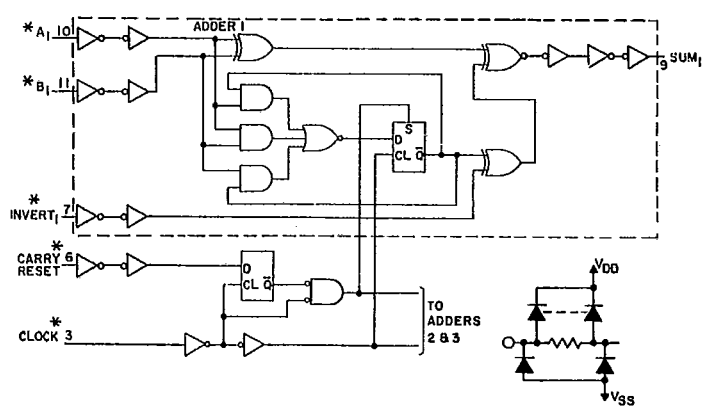


Fig.2 - CD4032B timing diagram.

* ALL INPUTS ARE PROTECTED BY COS/MOS PROTECTION NETWORK

92CM-29082R2

Fig.1 - CD4032B logic diagram of one of three serial adders.

T-45-07-

CD4032B, CD4038B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ\text{C}$, Input $t_r, t_f = 20\text{ ns}$,
 $C_L = 50\text{ pF}$, $R_L = 200\text{ k}\Omega$

CHARACTERISTIC	TEST CONDITIONS $V_{DD}(V)$	LIMITS			UNITS
		Min.	Typ.	Max.	
Propagation Delay Time: t_{PHL}, t_{PLH} A,B, Carry Reset, or Invert Inputs to Sum Outputs	5	—	260	520	ns
	10	—	120	240	
	15	—	90	180	
Clock Input to Sum Outputs	5	—	325	650	ns
	10	—	175	350	
	15	—	150	300	
Transition Time: t_{THL}, t_{TLH}	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Minimum Data Input Setup Time, t_{SU} Clock to A or B Inputs	5	—	125	200	ns
	10	—	50	80	
	15	—	40	60	
Maximum Clock Input Frequency, f_{CL}	5	2.5	4.5	—	MHz
	10	5	10	—	
	15	7.5	15	—	
Clock Input Rise or Fall Time, t_{rCL}, t_{fCL}^*	5	—	—	500	μs
	10	—	—	500	
	15	—	—	500	
Input Capacitance, C_{IN}	(Any Input)	—	5	7.5	pF

* If more than one unit is cascaded t_{rCL} should be made less than or equal to the sum of the transition time and the fixed propagation delay of the output of the driving stage for the estimated capacitive load.

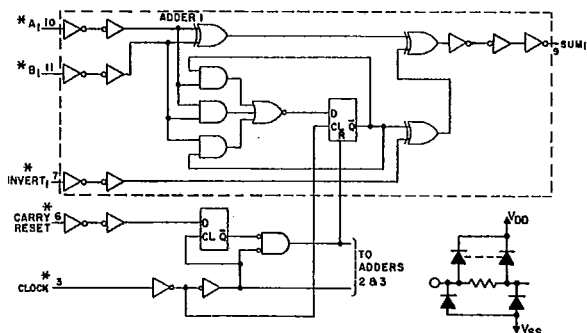


Fig. 3 - CD4038B logic diagram of one of three serial adders.

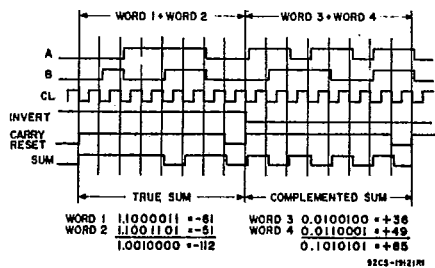


Fig. 4 - CD4038B timing diagram.

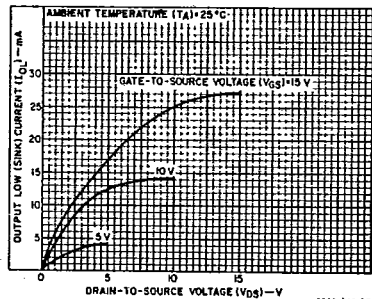


Fig. 5 - Typical output low (sink) current characteristics.

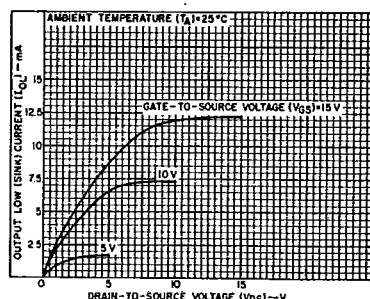


Fig. 6 - Minimum output low (sink) current characteristics.

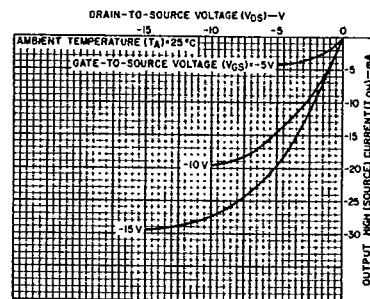


Fig. 7 - Typical output high (source) current characteristics.

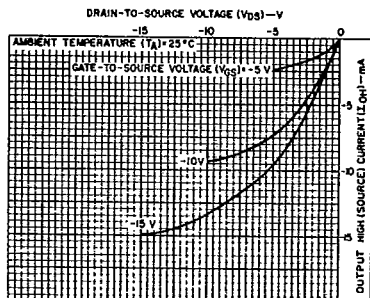


Fig. 8 - Minimum output high (source) current characteristics.

CD4032B, CD4038B Types

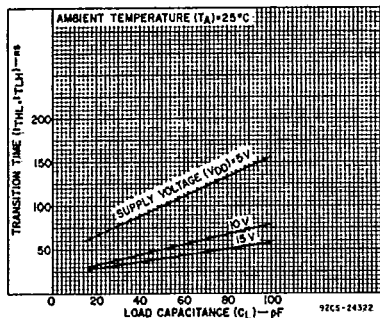


Fig. 9 - Typical transition time as a function of load capacitance.

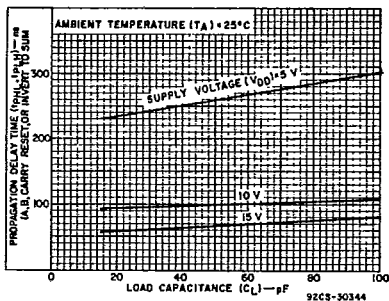


Fig. 10 - Typical propagation delay times as a function of load capacitance (A, B, carry reset or invert to SUM).

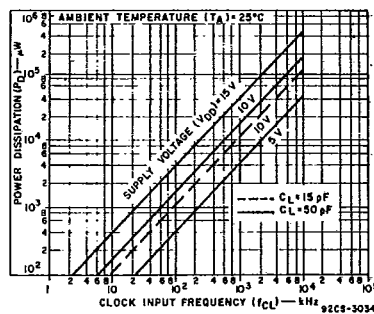


Fig. 11 - Typical dynamic power dissipation as a function of clock input frequency.

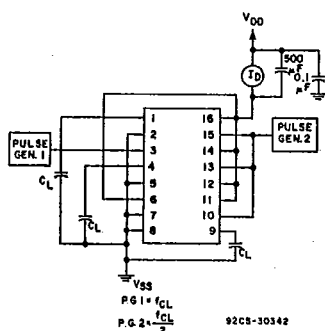


Fig. 12 - Dynamic power dissipation test circuit.

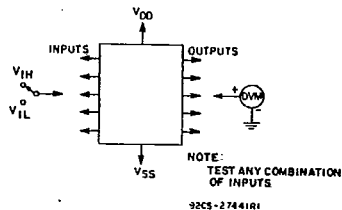


Fig. 13 - Input voltage test circuit.

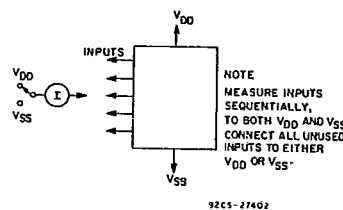


Fig. 14 - Input current test circuit.

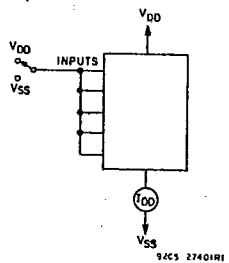
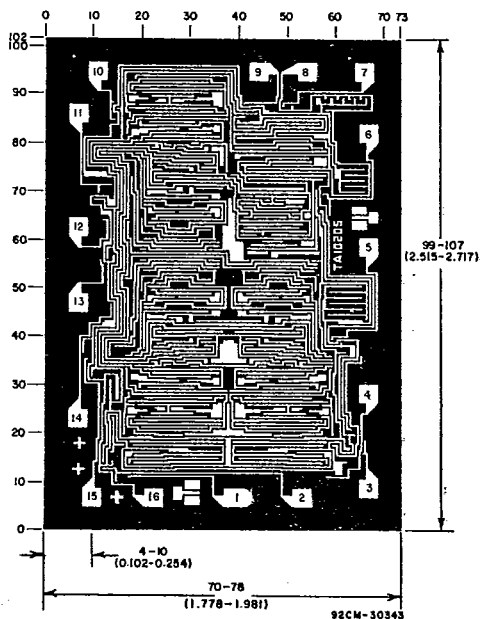


Fig. 15 - Quiescent-device current test circuit.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch).

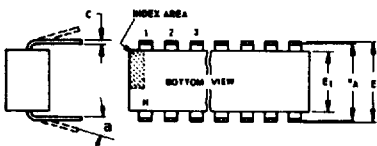
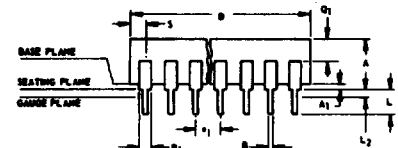
The photographs and dimensions of each CMOS chip represent a chip when it is part of the wafer. When the wafer is separated into individual chips, the angle of cleavage may vary with respect to the chip face for different chips. The actual dimensions of the isolated chip, therefore, may differ slightly from the nominal dimensions shown. The user should consider a tolerance of -3 mils to +16 mils applicable to the nominal dimensions shown.



Dimensions and pad layout for CD4032BH; dimensions and pad layout for CD4038BH are identical.

Dimensional Outlines

Dual-In-Line Welded-Seal Ceramic Packages



- NOTES:**
Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.
- When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
 - Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
 - e_A applies in zone L₂ when unit installed.
 - a applies to spread leads prior to installation.
 - N is the maximum quantity of lead positions.
 - N₁ is the quantity of allowable missing leads.

(D) SUFFIX (JEDEC MO-001-AD)
14-Lead Dual-In-Line Welded-Seal
Ceramic Package

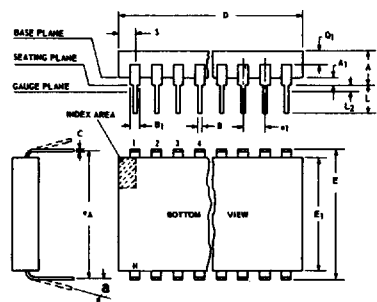
SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.160		3.05	4.06
A ₁	0.020	0.065		0.51	1.65
B	0.014	0.020		0.356	0.508
B ₁	0.060	0.065		1.27	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.770		18.93	19.55
E	0.300	0.325		7.62	8.25
E ₁	0.240	0.260		6.10	6.60
e ₁	0.100 TP		2	2.54 TP	
e _A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L ₂	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	14		5	14	
N ₁	0		6	0	
Q ₁	0.050	0.085		1.27	2.15
S	0.065	0.090		1.66	2.28

92SS-4411R2

(D) SUFFIX (JEDEC MO-001-AE)
16-Lead Dual-In-Line Welded-Seal
Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.160		3.05	4.06
A ₁	0.020	0.065		0.51	1.65
B	0.014	0.020		0.356	0.508
B ₁	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.785		18.93	19.93
E	0.300	0.325		7.62	8.25
E ₁	0.240	0.260		6.10	6.60
e ₁	0.100 TP		2	2.54 TP	
e _A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L ₂	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	16		5	16	
N ₁	0		6	0	
Q ₁	0.050	0.085		1.27	2.15
S	0.015	0.060		0.39	1.52

92SS-4266R5



- NOTES:**
Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.
- When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
 - Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
 - e_A applies in zone L₂ when unit installed.
 - a applies to spread leads prior to installation.
 - N is the maximum quantity of lead positions.
 - N₁ is the quantity of allowable missing leads.

(D) SUFFIX (JEDEC MO-015-AG)
24-Lead Dual-In-Line Welded-Seal
Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.090	0.200		2.29	5.08
A ₁	0.020	0.070		0.51	1.78
B	0.015	0.020		0.381	0.508
B ₁	0.045	0.055		1.143	1.397
C	0.008	0.012	1	0.204	0.304
D	1.15	1.22		29.21	30.98
E	0.600	0.625		15.24	15.87
E ₁	0.480	0.520		12.20	13.20
e ₁	0.100 TP		2	2.54 TP	
e _A	0.600 TP		2, 3	15.24 TP	
L	0.100	0.180		2.54	4.57
L ₂	0.000	0.030		0.00	0.76
a	0°	15°	4	0°	15°
N	24		5	24	
N ₁	0		6	0	
Q ₁	0.020	0.080		0.51	2.03
S	0.020	0.060		0.51	1.52

92CS-19948R4

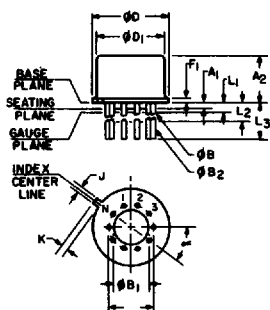
(D) SUFFIX (JEDEC MO-015-AH)
28-Lead Dual-In-Line Welded-Seal
Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.090	0.200		2.29	5
A ₁	0	0.070	2	0	1.77
B	0.015	0.020		0.381	0.508
B ₁	0.015	0.065		0.39	1.39
C	0.008	0.012	1	0.204	0.304
D	1.380	1.420		35.06	36.06
E	0.600	0.625		15.24	15.87
E ₁	0.485	0.515		12.32	13.08
e ₁	0.100 TP		2	2.54 TP	
e _A	0.600 TP		2, 3	15.24 TP	
L	0.100	0.200		2.6	5
L ₂	0	0.030		0	0.76
a	0°	15°	4	0°	15°
N	28		5	28	
N ₁	0		6	0	
Q ₁	0.020	0.070		0.51	1.77
S	0.040	0.070		1.02	1.77

92CM-20250R2

TO-5 Style Package

(T) SUFFIX (JEDEC MO-006-AG)
12-Lead Metal Package



92CS-19774

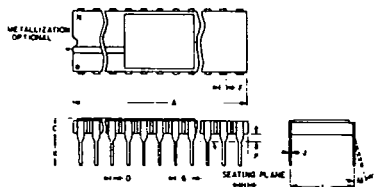
SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
a	0.230		2	5.84 TP	
A ₁	0	0		0	0
A ₂	0.165	0.185		4.19	4.70
φB	0.016	0.019	3	0.407	0.482
φB ₁	0	0		0	0
φB ₂	0.016	0.021	3	0.407	0.533
φD	0.335	0.370		8.51	9.39
φD ₁	0.305	0.335		7.75	8.50
F ₁	0.020	0.040		0.51	1.01
j	0.028	0.034		0.712	0.863
k	0.029	0.045	4	0.74	1.14
L ₁	0.000	0.050	3	0.00	1.27
L ₂	0.250	0.500	3	6.4	12.7
L ₃	0.500	0.562	3	12.7	14.27
a	30° TP			30° TP	
N	12		6	12	
N ₁	1		5	1	

NOTES:

- Refer to Rules for Dimensioning Axial Lead Product Outlines.
- Leads at gauge plane within 0.007" (0.178 mm) radius of True Position (TP) at maximum material condition.
- φB applies between L₁ and L₂. φB₂ applies between L₂ and 0.500" (12.70 mm) from seating plane. Diameter is uncontrolled in L₁ and beyond 0.500" (12.70 mm).
- Measure from Max. φD.
- N₁ is the quantity of allowable missing leads.
- N is the maximum quantity of lead positions.

Dimensional Outlines (Cont'd)

DUAL-IN-LINE SIDE-BRAZED CERAMIC PACKAGES



(D) SUFFIX
18-Lead Dual-In-Line
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.890	0.915		22.606	23.241
C	-	0.200		-	5.080
D	0.015	0.021		0.381	0.533
F	0.054	REF.	1	1.371	REF.
G	0.100	BSC	1	2.54	BSC
H	0.035	0.065		0.889	1.651
J	0.008	0.012	3	0.203	0.304
K	0.125	0.150		3.175	3.810
L	0.290	0.310	2	7.366	7.874
M	0°	15°		0°	15°
P	0.025	0.045		0.635	1.143
N	18			18	

92CS-27231R1

(D) SUFFIX
22-Lead Dual-In-Line
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.065	1.100		27.05	27.94
C	0.085	0.145		2.16	3.68
D	0.017	0.023		0.43	0.58
F	0.040	REF.	1	1.02	REF.
G	0.100	BSC	1	2.54	BSC
H	0.030	0.070		0.76	1.78
J	0.008	0.012	3	0.20	0.30
K	0.125	0.175		3.18	4.45
L	0.380	0.420	2	9.65	10.67
M	-	7°		-	7°
P	0.025	0.050		0.64	1.27
N	22			22	

92CS-25186R2

NOTES:

- Leads within 0.005" (0.13 mm)-radius of True Position at maximum material condition.
- Dimension "L" to center of leads when formed parallel.
- When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).

(D) SUFFIX
24-Lead Dual-In-Line
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.180	1.220		29.98	30.98
C	0.085	0.145		2.16	3.68
D	0.015	0.023		0.39	0.58
F	0.040	REF.		1.02	REF.
G	0.100	BSC	1	2.54	BSC
H	0.030	0.070		0.77	1.77
J	0.008	0.012	3	0.21	0.30
K	0.125	0.175		3.18	4.44
L	0.580	0.620	2	14.74	15.74
M	-	7°		-	7°
P	0.025	0.050		0.64	1.27
N	24			24	

92CS-30968R1

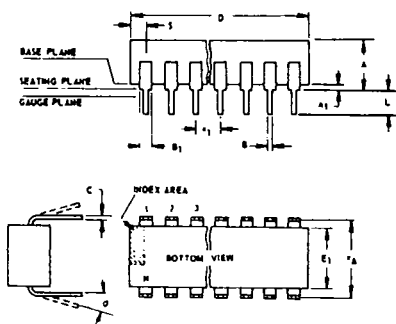
(D) SUFFIX
40-Lead Dual-In-Line
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.980	2.020		50.30	51.30
C	0.095	0.155		2.43	3.93
D	0.017	0.023		0.43	0.58
F	0.050	REF.		1.27	REF.
G	0.100	BSC	1	2.54	BSC
H	0.030	0.070		0.76	1.78
J	0.008	0.012	3	0.20	0.30
K	0.125	0.175		3.18	4.45
L	0.580	0.620	2	14.74	15.74
M	-	7°		-	7°
P	0.025	0.050		0.64	1.27
N	40			40	

92CM-27029R2

Dual-In-Line Plastic and Frit-Seal Ceramic Packages

(E) SUFFIX (JEDEC MO-001-AN)
8-Lead Dual-In-Line Plastic
(Mini-DIP) Package



SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A ₁	0.020	0.050		0.508	1.27
B	0.014	0.020		0.356	0.508
B ₁	0.035	0.065		0.889	1.65
C	0.008	0.012	1	0.203	0.304
D	0.370	0.400		9.40	10.16
E	0.300	0.325		7.62	8.25
E ₁	0.240	0.260		6.10	6.60
e ₁	0.100	TP	2	2.54	TP
e _A	0.300	TP	2, 3	7.62	TP
L	0.125	0.150		3.18	3.81
L ₂	0.000	0.030		0.000	0.762
a	0	15	4	0	15
N	8		5	8	
N ₁	0		6	0	
O ₁	0.040	0.075		1.02	1.90
S	0.015	0.060		0.381	1.52

92CS-24026 R1

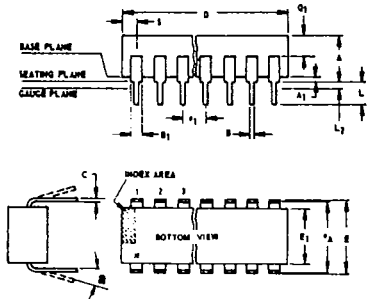
NOTES:

Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.

- When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013".
- Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
- e_A applies in zone L₂ when unit installed.
- a applies to spread leads prior to installation.
- N is the maximum quantity of lead positions.
- N₁ is the quantity of allowable missing leads.

Dimensional Outlines (Cont'd)

Dual-In-Line Plastic and Frit-Seal Ceramic Packages (Cont'd)



NOTES:
 Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.
 1. When this device is supplied solder dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
 2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
 3. e_A applies in zone L₂ when unit installed.
 4. a applies to spread leads prior to installation.
 5. N is the maximum quantity of lead positions.
 6. N₁ is the quantity of allowable missing leads.

**(E) and (F) SUFFIXES (JEDEC MO-001-AB)
 14-Lead Dual-In-Line Plastic or
 Frit-Seal Ceramic Package**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A ₁	0.020	0.050		0.51	1.27
B	0.014	0.020		0.356	0.508
B ₁	0.050	0.065		1.27	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.770		18.93	19.55
E	0.300	0.325		7.62	8.25
E ₁	0.240	0.260		6.10	6.60
e ₁	0.100 TP		2	2.54 TP	
e _A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L ₂	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	14		5	14	
N ₁	0		6	0	
Q ₁	0.040	0.075		1.02	1.90
S	0.065	0.090		1.66	2.28

92SS-4296R3

**(E) and (F) SUFFIXES (JEDEC MO-001-AC)
 16-Lead Dual-In-Line Plastic or
 Frit-Seal Ceramic Package**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A ₁	0.020	0.050		0.51	1.27
B	0.014	0.020		0.356	0.508
B ₁	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.785		18.93	19.93
E	0.300	0.325		7.62	8.25
E ₁	0.240	0.260		6.10	6.60
e ₁	0.100 TP		2	2.54 TP	
e _A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L ₂	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	16		5	16	
N ₁	0		6	0	
Q ₁	0.040	0.075		1.02	1.90
S	0.015	0.060		0.39	1.52

92CM-15967R4

**(E) SUFFIX
 18-Lead Dual-In-Line
 Plastic Package**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A ₁	0.020	0.050		0.508	1.27
B	0.014	0.020		0.356	0.508
B ₁	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D	0.845	0.885		21.47	22.47
E ₁	0.240	0.260		6.10	6.60
e ₁	0.100 TP		2	2.54 TP	
e _A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
a	0°	15°	4	0°	15°
N	18		5	18	
N ₁	0		6	0	
S	0.015	0.060		0.39	1.52

92CS-30630

**(E) SUFFIX
 22-Lead Dual-In-Line
 Plastic Package**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A ₁	0.020	0.050		0.508	1.27
B	0.015	0.020		0.381	0.508
B ₁	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D		1.120			28.44
E	0.390	0.420		9.91	10.66
E ₁	0.345	0.355		8.77	9.01
e ₁	0.100 TP		2	2.54 TP	
e _A	0.400 TP		2, 3	10.16 TP	
L	0.125	0.150		3.18	3.81
L ₂	0	0.030		0	0.762
a	2°	15°	4	2°	15°
N	22		5	22	
N ₁	0		6	0	
Q ₁	0.055	0.085		1.40	2.15
S	0.015	0.060		0.381	1.27

92CS-30830

**(F) SUFFIX (JEDEC MO-001-AG)
 16-Lead Dual-In-Line
 Frit-Seal Ceramic Package**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.165	0.210		4.20	5.33
A ₁	0.015	0.045		0.381	1.14
B	0.015	0.020		0.381	0.508
B ₁	0.045	0.070		1.15	1.77
C	0.009	0.011	1	0.229	0.279
D	0.750	0.795		19.05	20.19
E	0.295	0.325		7.50	8.25
E ₁	0.245	0.300		6.23	7.62
e ₁	0.100 TP		2	2.54 TP	
e _A	0.300 TP		2, 3	7.62 TP	
L	0.120	0.160		3.05	4.06
L ₂	0.000	0.030		0.000	0.76
a	2°	15°	4	2°	15°
N	16		5	16	
N ₁	0		6	0	
Q ₁	0.050	0.080		1.27	2.03
S	0.010	0.060		0.254	1.52

92CM-22284R1

**(E) and (F) SUFFIXES (JEDEC MO-015-AA)
 24-Lead Dual-In-Line Plastic or
 Frit-Seal Ceramic Package**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.250		3.10	6.30
A ₁	0.020	0.070		0.51	1.77
B	0.016	0.020		0.407	0.508
B ₁	0.028	0.070		0.72	1.77
C	0.008	0.012	1	0.204	0.304
D	1.20	1.29		30.48	32.76
E	0.600	0.625		15.24	15.87
E ₁	0.515	0.580		13.09	14.73
e ₁	0.100 TP		2	2.54 TP	
e _A	0.600 TP		2, 3	15.24 TP	
L	0.100	0.200		2.54	5.00
L ₂	0.000	0.030		0.00	0.76
a	0°	15°	4	0°	15°
N	24		5	24	
N ₁	0		6	0	
Q ₁	0.040	0.075		1.02	1.90
S	0.040	0.100		1.02	2.54

92CS26938R2

**(E) SUFFIX
 40-Lead Dual-In-Line
 Plastic Package**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.250		3.10	6.30
A ₁	0.020	0.070		0.51	1.77
B	0.016	0.020		0.407	0.508
B ₁	0.028	0.070		0.72	1.77
C	0.008	0.012	1	0.204	0.304
D	2.000	2.090		50.80	53.09
E ₁	0.515	0.580		13.09	14.73
e ₁	0.100 TP		2	2.54 TP	
e _A	0.600 TP		2, 3	15.24 TP	
L	0.100	0.200		2.54	5.00
L ₂	0.000	0.030		0.00	0.76
a	0°	15°	4	0°	15°
N	40		5	40	
N ₁	0		6	0	
Q ₁	0.065	0.095		1.66	2.41
S	0.040	0.100		1.02	2.54

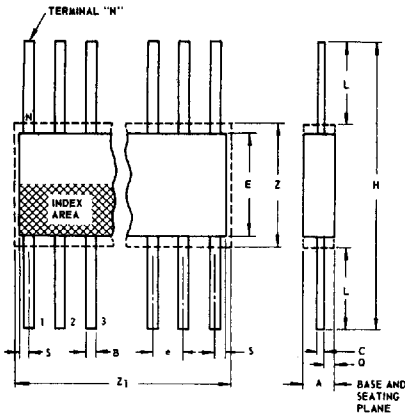
92CS-30959

T-90-20

Dimensional Outlines (Cont'd)

Ceramic Flat Packs

**(K) SUFFIX (JEDEC MO-004-AF)
14-Lead**



SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.008	0.100		0.21	2.54
B	0.015	0.019	1	0.381	0.482
C	0.003	0.006	1	0.077	0.152
e	0.050 TP		2	1.27 TP	
E	0.200	0.300		5.1	7.6
H	0.600	1.000		15.3	25.4
L	0.150	0.350		3.9	8.8
N	14		3	14	
Q	0.005	0.050		0.13	1.27
S	0.000	0.050		0.00	1.27
Z	0.300		4	7.62	
Z ₁	0.400		4	10.16	

928S-4300R3

NOTES:

1. Refer to JEDEC Publication No. 95 for Rules for Dimensioning Peripheral Lead Outlines.
2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at maximum material condition.
3. N is the maximum quantity of lead positions.
4. Z and Z₁ determine a zone within which all body and lead irregularities lie.

**(K) SUFFIX (JEDEC MO-004-AG)
16-Lead**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.008	0.100		0.21	2.54
B	0.015	0.019	1	0.381	0.482
C	0.003	0.006	1	0.077	0.152
e	0.050 TP		2	1.27 TP	
E	0.200	0.300		5.1	7.6
H	0.600	1.000		15.3	25.4
L	0.150	0.350		3.9	8.8
N	16		3	16	
Q	0.005	0.050		0.13	1.27
S	0.000	0.025		0.00	0.63
Z	0.300		4	7.62	
Z ₁	0.400		4	10.16	

92CS-17271R3

**(K) SUFFIX
24-Lead**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.075	0.120		1.91	3.04
B	0.018	0.022	1	0.458	0.558
C	0.004	0.007	1	0.102	0.177
e	0.050 TP		2	1.27 TP	
E	0.600	0.700		15.24	17.78
H	1.150	1.350		29.21	34.29
L	0.225	0.325		5.72	8.25
N	24		3	24	
Q	0.035	0.070		0.89	1.77
S	0.060	0.110	1	1.53	2.79
Z	0.700		4	17.78	
Z ₁	0.750		4	19.05	

92CS-19949R2

**(K) SUFFIX
28-Lead**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.075	0.120		1.91	3.04
B	0.018	0.022	1	0.458	0.558
C	0.004	0.007	1	0.102	0.177
e	0.050 TP		2	1.27 TP	
E	0.600	0.700		15.24	17.78
H	1.150	1.350		29.21	34.29
L	0.225	0.325		5.72	8.25
N	28		3	28	
Q	0.035	0.070		0.89	1.77
S	0	0.060	1	0	1.53
Z	0.700		4	17.78	
Z ₁	0.750		4	19.05	

92CS-20972